

Project Overview

Background:

ASML is the leading provider of EUV (extreme ultraviolet) lithography equipment used in the production of advanced, semiconductor chips worldwide.

As part of troubleshooting, research, and development, ASML employs a heated vacuum chamber to simulate the various operating conditions where the Multilayer Mirror samples are used.

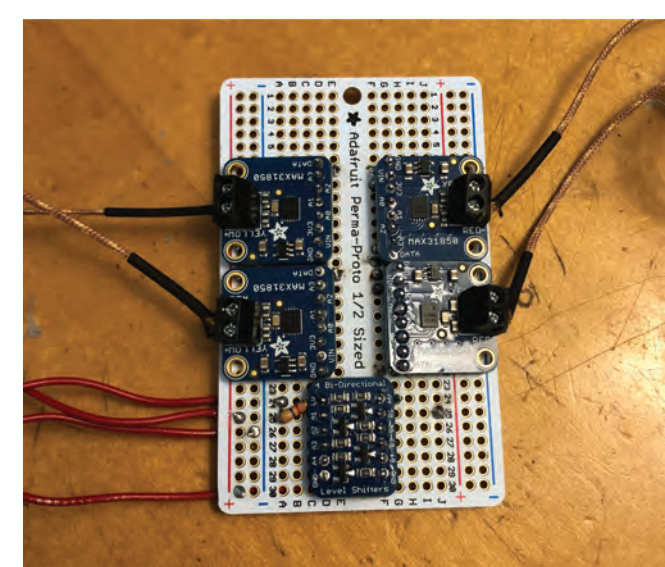
Problem Statement:

Create a water-cooled baseplate capable of holding a variety of mirror shapes and sizes at 30°C - 50°C while exposed to a maximum temperature of 300°C under vacuum.

Manufacturing



Soldering Lead Pins



Perfboard Circuit



3D Printed Housing



Cutting Stock Material



Machined Baseplate



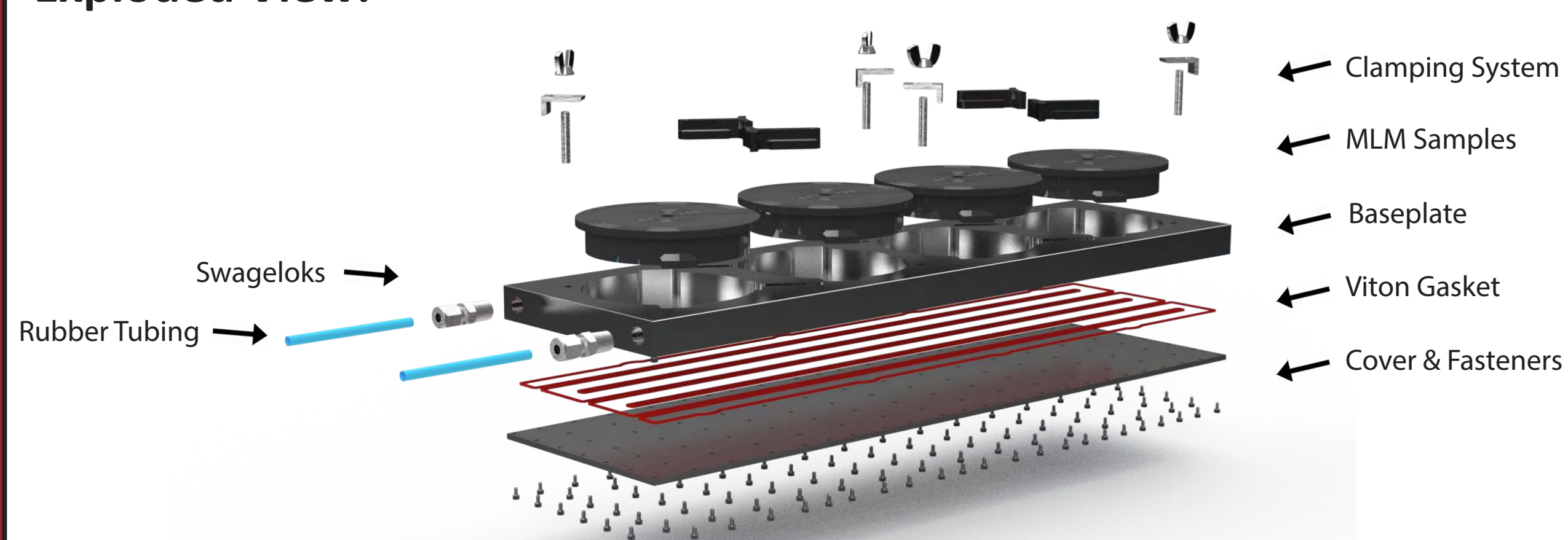
CNC Milling Custom Clamps

CAD Models

3D Render:

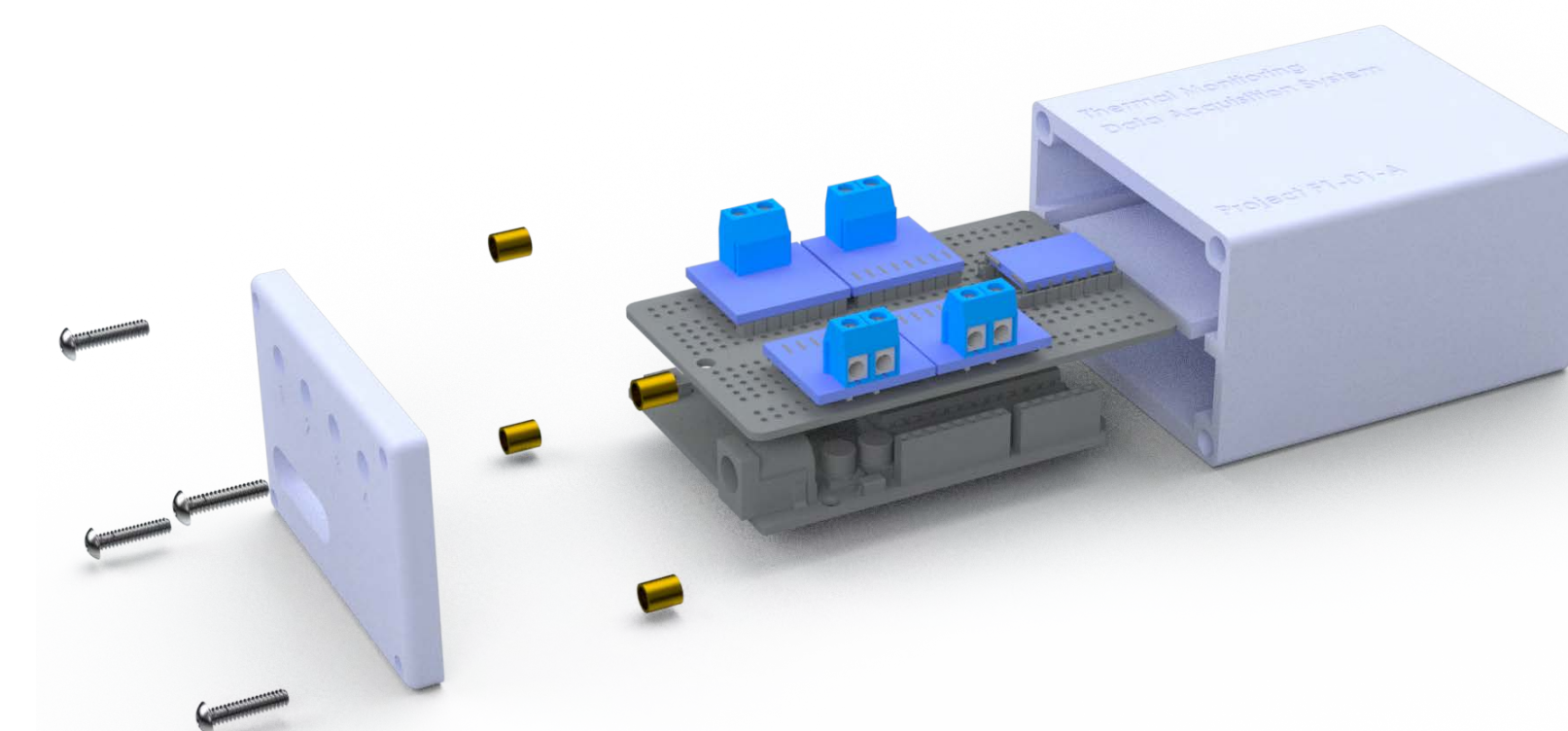


Exploded View:



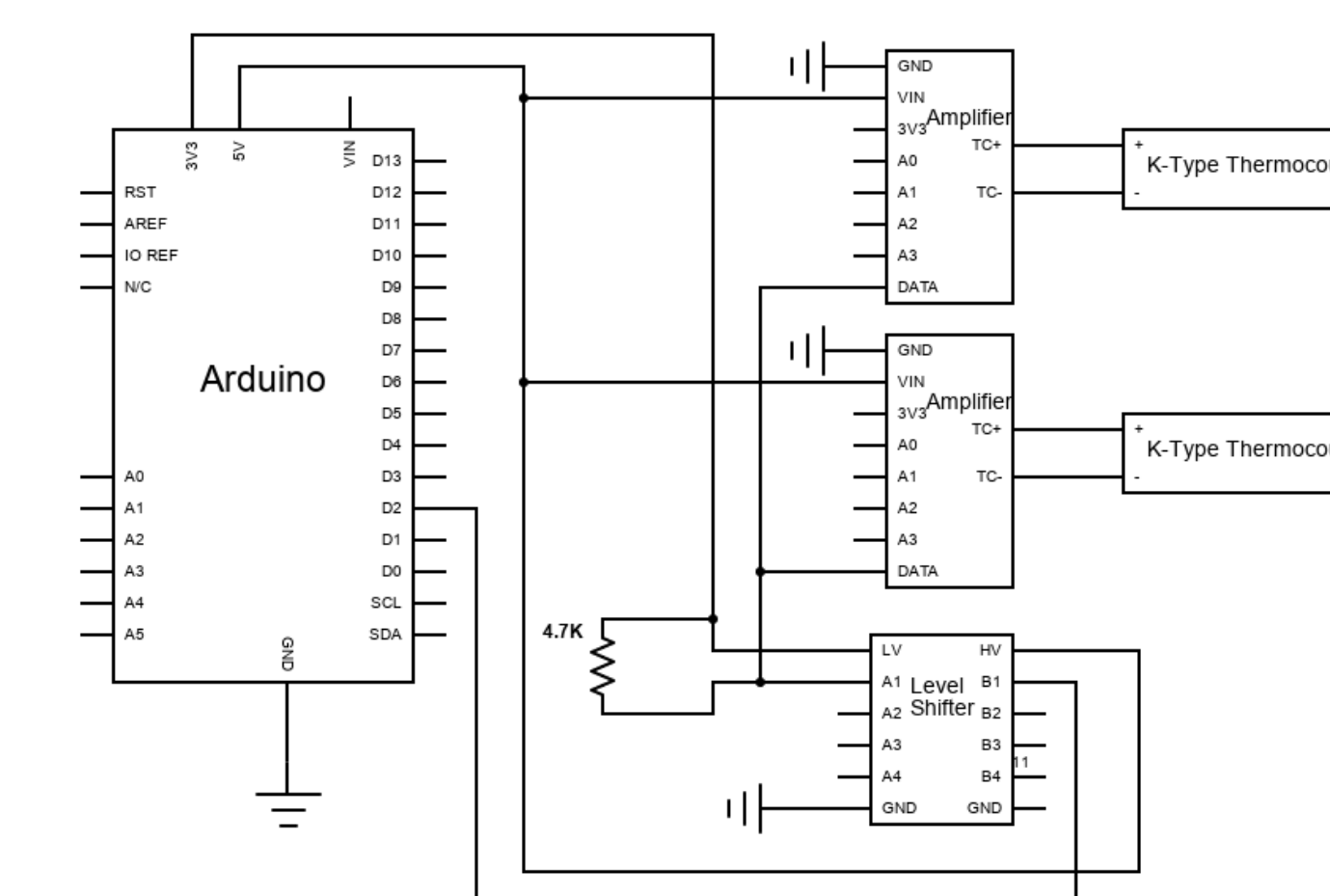
Data Acquisition

3D Render:

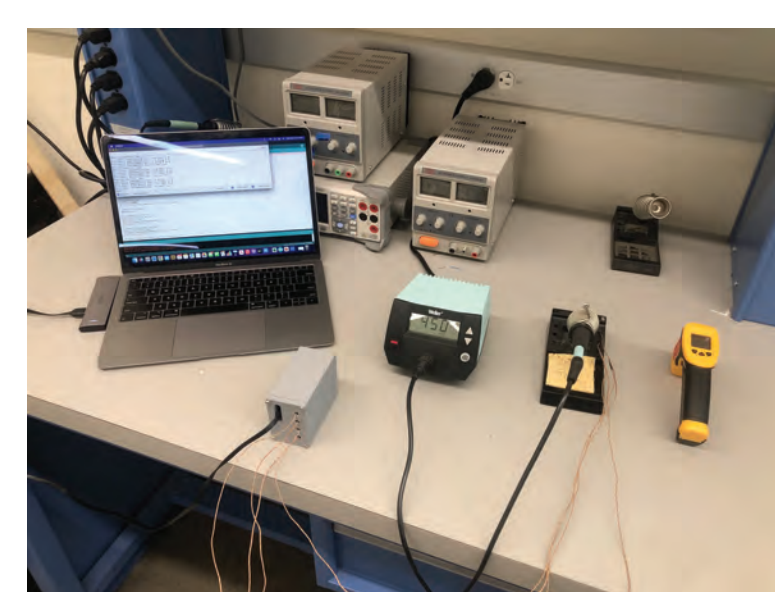


To monitor mirror sample temperatures during testing, a data acquisition system was created using the MAX31850 breakout board and an Arduino microprocessor. This allowed for all temperature-related testing to be conducted on-campus before being verified with ASML on-site.

Wiring Diagram:



Testing



Data Acquisition Validation



Heat Resistance & Leak Check On Campus



Full System Validation On Site at ASML

Thermal Analysis

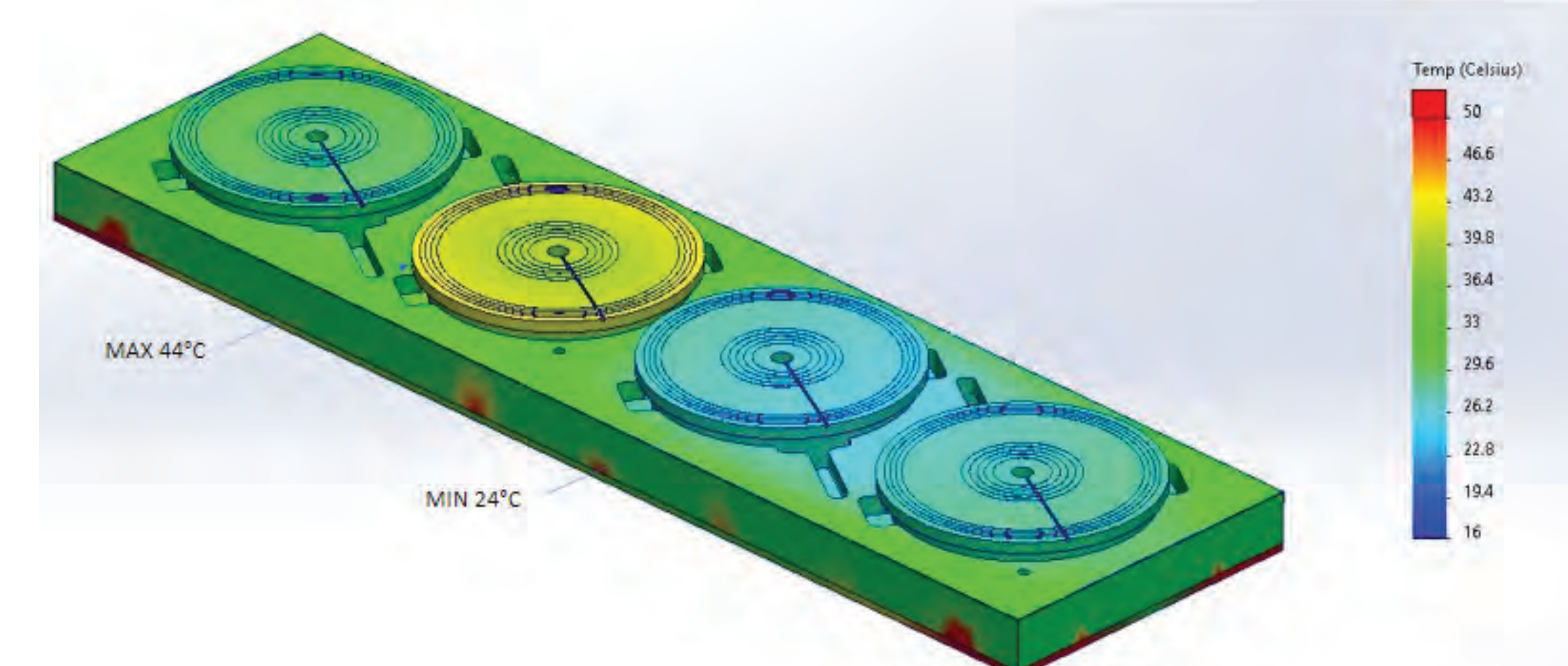
Test Chamber Boundary Conditions:

18 LPM of 16.5°C cooling water is supplied through a $\phi 12.7$ mm inlet.

Convection Coefficient of 300 W/m²K assigned to all inner surfaces.

Heat Power of 3000 W assigned to all exposed surfaces.

Constant Temperature of 300°C assigned to chamber walls (not shown).



The thermal simulation shows a sample surface temperature range of 24 °C to 44 °C. This satisfies all thermal design requirements at maximum test conditions.

Gasket Design:

Torque required per fastener was calculated using compression curves.

Team Members



Hunter Atchley
Lead Engineer



Brenden Funke
Procurement & Research Engineer



Jorge Pineda
Supply & Finance Engineer



Andrew Preisler
Design & Manufacturing Engineer



Aaron Ramirez
Quality & Test Engineer

Acknowledgements

The team would like to thank the following people for their contributions.

ASML:

Joe Bendik - Project Sponsor
Tony Balanza - Test Chamber Specialist

SDSU:

Dr. Scott Shaffar - Project Advisor
Mike Lester - Manufacturing Assistance
Selena Jarin - Purchasing Assistance